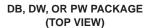
SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE AND 3-STATE OUTPUTS

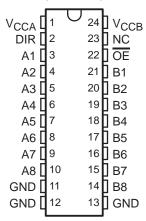
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- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Bidirectional Voltage Translator
- 2.3 V to 3.6 V on A Port and 3 V to 5.5 V on B Port
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17

ESD Protection Exceeds JESD 22

- 2000-V Human-Body Model (A114-A)
- 200-V Machine Model (A115-A)
- 1000-V Charged-Device Model (C101)





NC - No internal connection

description/ordering information

This 8-bit (octal) noninverting bus transceiver contains two separate supply rails. The B port is designed to track V_{CCB} , which accepts voltages from 3 V to 5.5 V, and the A port is designed to track V_{CCA} , which operates at 2.3 V to 3.6 V. This allows for translation from a 3.3-V to a 5-V system environment and vice versa, from a 2.5-V to a 3.3-V system environment and vice versa.

The SN74LVCC3245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are isolated. The control circuitry (DIR, \overline{OE}) is powered by V_{CCA} .

ORDERING INFORMATION

TA	PACKAGE	t	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - DW	Reel of 2000	CLVCC3245AIDWREP	LVCC3245A
-40°C to 85°C	SSOP - DB	Reel of 2000	CLVCC3245AIDBREP	LH245AEP
	TSSOP - PW	Reel of 2000	CLVCC3245AIPWREP	LH245AEP

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



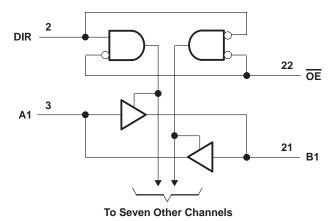
[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

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FUNCTION TABLE (each transceiver)

INP	UTS	ODED ATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CCA} and V _{CCB}	–0.5 V to 6 V
Input voltage range, V _I : All A ports (see Note 1)	-0.5 V to $V_{\text{CCA}} + 0.5 \text{ V}$
All B ports (see Note 2)	$-0.5 \text{ V to V}_{CCB} + 0.5 \text{ V}$
Except I/O ports (see Note 1)	-0.5 V to V _{CCA} + 0.5 V
Output voltage range, V _O (see Note 2): All A ports	-0.5 V to V _{CCA} + 0.5 V
All B ports	$-0.5 \text{ V to V}_{CCB} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	
Continuous current through V _{CCA} , V _{CCB} , or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DB package	63°C/W
DW package	46°C/W
PW package	
Storage temperature range, T _{Stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. This value is limited to 4.6 V maximum.
 - 2. This value is limited to 6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

recommended operating conditions (see Note 4)

		VCCA	VCCB	MIN	NOM	MAX	UNIT
VCCA	Supply voltage			2.3	3.3	3.6	V
VCCB	Supply voltage			3	5	5.5	V
		2.3 V	3 V	1.7			
.,		2.7 V	3 V	2			.,
V_{IHA}	High-level input voltage	3 V	3.6 V	2			V
		3.6 V	5.5 V	2			
		2.3 V	3 V	2			
.,	USala Taras Caras Caras Caras Caras Caras	2.7 V	3 V	2			
VIHB	High-level input voltage	3 V	3.6 V	2			V
		3.6 V	5.5 V	3.85			
		2.3 V	3 V			0.7	
.,	Laurence la contra de la contra dela contra de la contra del la contra del la contra del la contra de la contra del la contra de la contra de la contra del la contra		3 V			0.8	V
V _{ILA}	Low-level input voltage	3 V	3.6 V			0.8	V
		3.6 V	5.5 V			0.8	
		2.3 V	3 V			0.8	
.,	Lava lava Caractora Rama	2.7 V	3 V			0.8	V
V_{ILB}	Low-level input voltage	3 V	3.6 V			0.8	
		3.6 V	5.5 V			1.65	
		2.3 V	3 V	1.7			
V	High-level input voltage (control pins)	2.7 V	3 V	2			V
V_{IH}	(Referenced to V _{CCA})	3 V	3.6 V	2			V
		3.6 V	5.5 V	2			
		2.3 V	3 V			0.7	
V/	Low-level input voltage (control pins)	2.7 V	3 V			0.8	V
V_{IL}	(Referenced to V _{CCA})		3.6 V			0.8	V
		3.6 V	5.5 V			0.8	
V_{IA}	Input voltage			0		VCCA	V
V_{IB}	Input voltage			0		VCCB	V
V_{OA}	Output voltage			0		VCCA	V
VOB	Output voltage			0		VCCB	V

NOTE 4: All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

recommended operating conditions (see Note 4) (continued)

		VCCA	VCCB	MIN	NOM	MAX	UNIT
		2.3 V	3 V			-8	
IOHA	High-level output current	2.7 V	3 V			-12	mA
		3.3 V	3 V			-24	
		2.3 V	3.3 V			-12	
IOHB	High-level output current	2.7 V	3.3 V			-12	mA
		3.3 V	3 V			-24	
		2.3 V	3 V			8	mA
IOLA	Low-level output current	2.7 V	3 V			12	
		3.3 V	3 V			24	
		2.3 V	3.3 V			12	
IOLB	Low-level output current	2.7 V	3.3 V			12	mA
		3.3 V	3 V			24	
Δt/Δν	Input transition rise or fall rate					10	ns/V
T _A	Operating free-air temperature			-40		85	°C

NOTE 4: All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE AND 3-STATE OUTPUTS SCAS773A – JUNE 2004 – REVISED MARCH 2005

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	VCCA	V _{CCB}	MIN	TYP	MAX	UNIT
		$I_{OH} = -100 \mu\text{A}$	3 V	3 V	2.9	3		
		$I_{OH} = -8 \text{ mA}$	2.3 V	3 V	2			
V		10	2.7 V	3 V	2.2	2.5		.,
V_{OHA}		I _{OH} = −12 mA	3 V	3 V	2.4	2.8		V
		04 4	3 V	3 V	2.2	2.6		
		I _{OH} = -24 mA	2.7 V	4.5 V	2	2.3		
		$I_{OH} = -100 \mu\text{A}$	3 V	3 V	2.9	3		
		Jan. 12 mA	2.3 V	3 V	2.4			
Vонв		I _{OH} = -12 mA	2.7 V	3 V	2.4	2.8		V
		Jan. 24 mA	3 V	3 V	2.2	2.6		
		I _{OH} = -24 mA	2.7 V	4.5 V	3.2	4.2		
		$I_{OL} = 100 \mu\text{A}$	3 V	3 V			0.1	
		$I_{OL} = 8 \text{ mA}$	2.3 V	3 V			0.6	
VOLA		$I_{OL} = 12 \text{ mA}$	2.7 V	3 V		0.1	0.5	V
		la. 24 mA	3 V	3 V		0.2	0.5	
		I _{OL} = 24 mA	2.7 V	4.5 V		0.2	0.5	i
V _{OLB}		$I_{OL} = 100 \mu\text{A}$	3 V	3 V			0.1	
		$I_{OL} = 12 \text{ mA}$	2.3 V	3 V			0.4	V
			3 V	3 V		0.2	0.5	V
		I _{OL} = 24 mA	3 V	4.5 V		0.2	0.5	
1.	Control inputs	W = Voor or CND	3.6 V	3.6 V		±0.1	±1	^
l _l	Control inputs	V _I = V _{CCA} or GND	3.0 V	5.5 V		±0.1	±1	μΑ
loz^{\dagger}	A or B ports	$V_O = V_{CCA/B}$ or GND, $V_I = V_{IL}$ or V_{IH}	3.6 V	3.6 V		±0.5	±5	μΑ
		A port = V_{CCA} or GND, $I_{O} = 0$	3.6 V	Open		5	50	
ICCA	B to A	Brant V m CND I 0	0.01/	3.6 V		5	50	μΑ
		B port = V_{CCB} or GND, $I_{O} = 0$	3.6 V	5.5 V		5	50	
		A	0.01/	3.6 V		5	50	
ICCB	A to B	A port = V_{CCA} or GND, $I_{O} = 0$	3.6 V	5.5 V		8	80	μΑ
	A port	$\frac{V_L}{OE}$ = V _{CCA} – 0.6 V, Other inputs at V _{CCA} or GND, $\frac{V_C}{OE}$ at GND and DIR at V _{CCA}	3.6 V	3.6 V		0.35	0.5	
ΔI _{CCA} ‡	ŌĒ	$V_I = V_{CCA} - 0.6 \text{ V}$, Other inputs at V_{CCA} or GND, DIR at V_{CCA}		3.6 V		0.35	0.5	mA
	DIR	$\frac{V_L}{OE}$ = V _{CCA} - 0.6 V, Other inputs at V _{CCA} or GND,	3.6 V	3.6 V		0.35	0.5	
ΔI _{CCB} ‡	B port	V_L = V _{CCB} – 2.1 V, Other inputs at V _{CCB} or GND, OE at GND and DIR at GND	3.6 V	5.5 V		1	1.5	mA
Ci	Control inputs	V _I = V _{CCA} or GND	Open	Open		4		pF
Cio	A or B ports	VO = VCCA/B or GND	3.3 V	5 V		18.5		pF



[†] For I/O ports, the parameter I_{OZ} includes the input leakage current.
‡ This is the increase in supply current for each input that is at one of the specified voltage levels, rather than 0 V or the associated V_{CC}.

SN74LVCC3245A-EP OCTAL BUS TRANSCEIVER WITH ADJUSTABLE OUTPUT VOLTAGE AND 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

PARAMETER			± 0.	= 2.5 V 2 V, = 3.3 V 3 V			V _{CCA} TO 3 V _{CCB} ± 0.	.6 V, = 3.3 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
^t PHL	•	c c	1	9.4	1	6	1	7.1	
^t PLH	А	В	1	9.1	1	5.3	1	7.2	ns
^t PHL	В	٨	1	11.2	1	5.8	1	6.4	20
^t PLH	Б	A	1	9.9	1	7	1	7.6	ns
tPZL	ŌĒ	^	1	14.5	1	9.2	1	9.7	
^t PZH	OE	А	1	12.9	1	9.5	1	9.5	ns
t _{PZL}	<u>OE</u>	c c	1	13	1	8.1	1	9.2	
^t PZH	OE	В	1	12.8	1	8.4	1	9.9	ns
tPLZ	ŌĒ		1	7.1	1	7	1	6.6	
^t PHZ	OE	А	1	6.9	1	7.8	1	6.9	ns
tpLZ	ŌĒ		1	8.8	1	7.3	1	7.5	
^t PHZ	OE	В	1	8.9	1	7	1	7.9	ns

operating characteristics, V_{CCA} = 3.3 V, V_{CCB} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT	
C. Bours dissipation consistence and transport	Outputs enabled	0 50	4 40 MH-	38		
Cpd	C _{pd} Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50,$	f = 10 MHz	4.5	pΕ

power-up considerations†

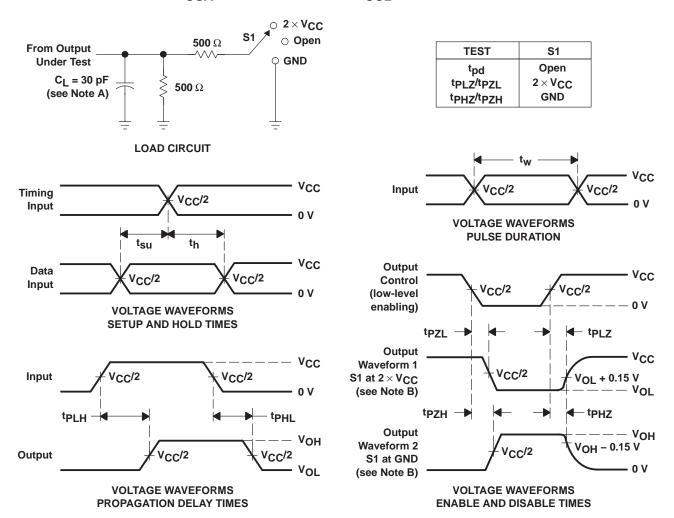
TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. To guard against such power-up problems, take these precautions:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V_{CCA} for all four of these devices).
- 3. Tie \overline{OE} to V_{CCA} with a pullup resistor so that it ramps with V_{CCA} .
- 4. Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with V_{CCA} . Otherwise, keep DIR low.

[†] Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.



PARAMETER MEASUREMENT INFORMATION FOR A PORT V_{CCA} = 2.5 V \pm 0.2 V AND V_{CCB} = 3.3 V \pm 0.3 V



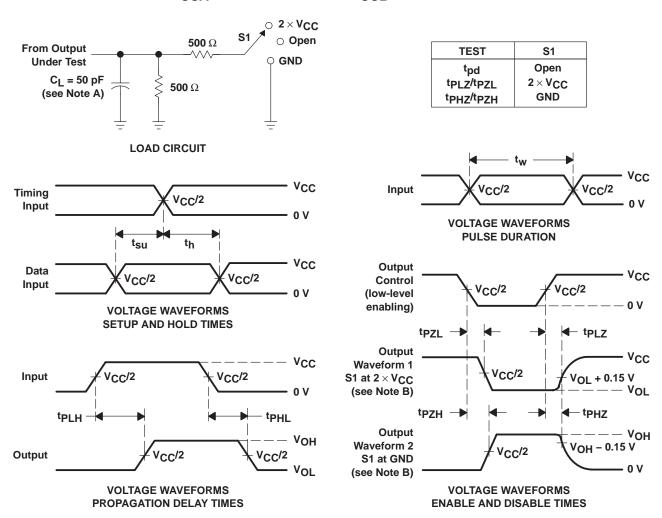
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION FOR B PORT V_{CCA} = 2.5 V \pm 0.2 V AND V_{CCB} = 3.3 V \pm 0.3 V



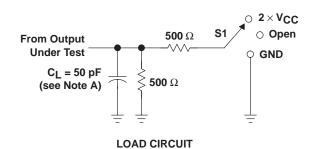
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

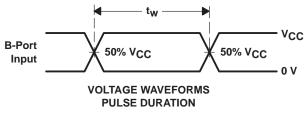
Figure 2. Load Circuit and Voltage Waveforms

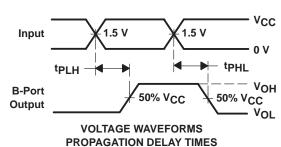


PARAMETER MEASUREMENT INFORMATION FOR B PORT $V_{CCA} = 3.6 \text{ V}$ AND $V_{CCB} = 5.5 \text{ V}$

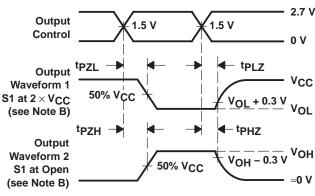


TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	Open





NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

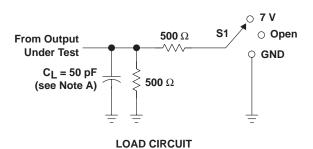
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

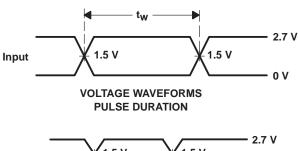
Figure 3. Load Circuit and Voltage Waveforms

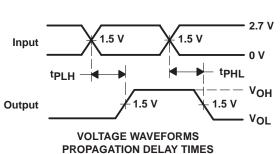
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PARAMETER MEASUREMENT INFORMATION FOR A AND B PORT V_{CCA} AND $V_{CCB} = 3.6 \text{ V}$

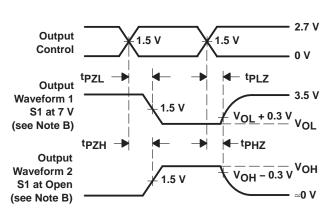


TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	7 V
tPHZ/tPZH	Open





NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns,
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CLVCC3245AIDBREP	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH245AEP	Samples
CLVCC3245AIDWREP	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCC3245A	Samples
CLVCC3245AIPWREP	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH245AEP	Samples
V62/05602-01XE	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH245AEP	Samples
V62/05602-01YE	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH245AEP	Samples
V62/05602-01ZE	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCC3245A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

6-Feb-2020

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVCC3245A-EP:

Catalog: SN74LVCC3245A

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 20-Feb-2019

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVCC3245AIDBREP	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
CLVCC3245AIDWREP	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CLVCC3245AIPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

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*All dimensions are nominal

ń									
	Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
	CLVCC3245AIDBREP	SSOP	DB	24	2000	367.0	367.0	38.0	
	CLVCC3245AIDWREP	SOIC	DW	24	2000	350.0	350.0	43.0	
	CLVCC3245AIPWREP	TSSOP	PW	24	2000	367.0	367.0	38.0	



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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